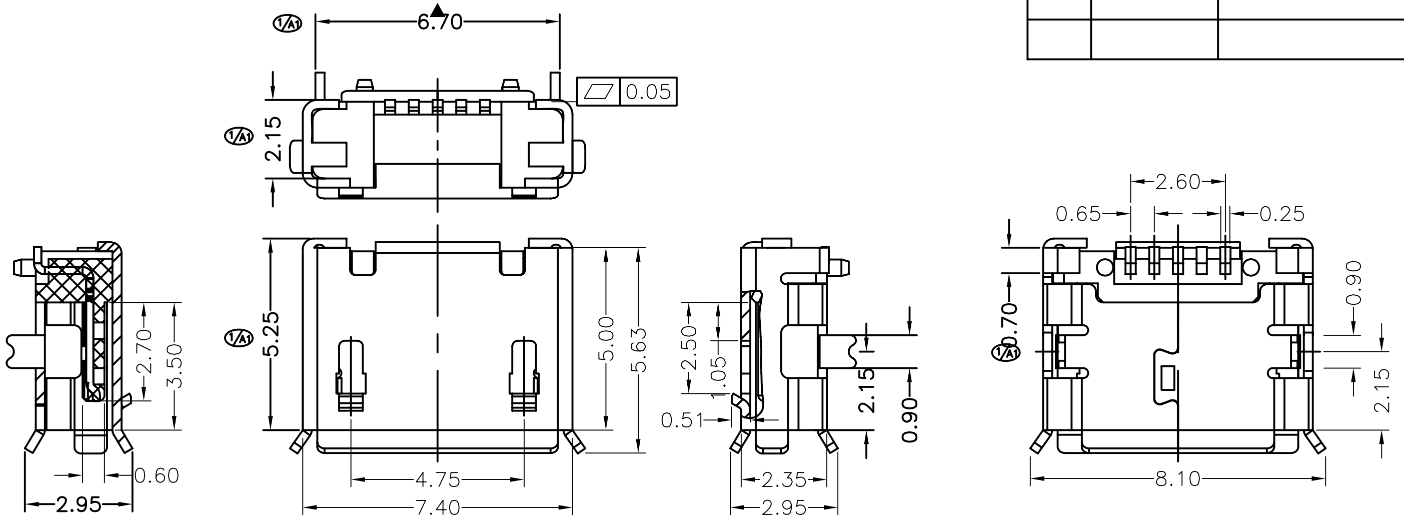
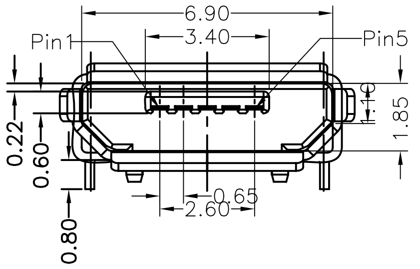
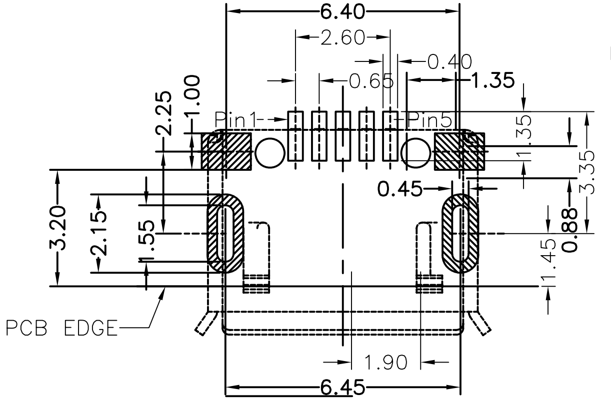
文件类型: 产品图面

REV.	ECNNO.	DESCRIPTION	DRWN	APPD.	DATE.







RECOMMANDED PCB LAYOUT

Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v−0

1.2 Contact: copper alloy,t=0.20mm

1.3 Shell: stainless steel ,t=0.25mm

2.Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extration cycles

2.7 Temperature range: −30°C~80°C

UNITS MM
SCALE 1:1

深圳市鑫南天科技有限公司
Shenzhen XinNanTian Industrial Co.,Ltd

GENERAL TOLERANCE
X. ±0.30
X.X ±0.20
X.XX ±0.10
X.° ±3°
X.X° ±2°

DR. Aaron
CHK. Aaron
APPD. PANYUFENG

TITLE: MICRO 5F BF前插后贴6.45有柱(0.8*0.9)
MAT'L:
DWG NO:
DATE: 2013.01.28
P
PART NO: XNTMICRO5P645
SIZE A4